

# SS26T3G, NRVBSS26T3G

## Surface Mount Schottky Power Rectifier SMB Power Surface Mount Package

... employing the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

### Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Overvoltage Protection
- Low Forward Voltage Drop
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- Pb-Free Package is Available

### Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL 94, V-O at 0.125 in
- Weight: 95 mg (approximately)
- Cathode Polarity Band
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Available in 12 mm Tape, 2500 Units per 13" Reel, Add "T3" Suffix to Part Number
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- ESD Ratings: Human Body Model = 3B  
Machine Model = C
- Marking: SS26

### MAXIMUM RATINGS

| Rating  | Symbol                          | Value       | Unit             |
|---|---------------------------------|-------------|------------------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage                      | $V_{RRM}$<br>$V_{RWM}$<br>$V_R$ | 60          | V                |
| Average Rectified Forward Current<br>(At Rated $V_R$ , $T_L = 95^\circ\text{C}$ )                           | $I_O$                           | 2.0         | A                |
| Non-Repetitive Peak Surge Current<br>(Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | $I_{FSM}$                       | 40          | A                |
| Storage/Operating Case Temperature  | $T_{stg}$ , $T_C$               | -55 to +150 | °C               |
| Operating Junction Temperature  | $T_J$                           | -55 to +150 | °C               |
| Voltage Rate of Change<br>(Rated $V_R$ , $T_J = 25^\circ\text{C}$ )   | dv/dt                           | 10,000      | V/ $\mu\text{s}$ |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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## SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES 60 VOLTS



SMB  
CASE 403A

### MARKING DIAGRAM



SS26 = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
▪ = Pb-Free Package  
(Note: Microdot may be in either location)

### ORDERING INFORMATION

| Device      | Package          | Shipping†          |
|-------------|------------------|--------------------|
| SS26T3G     | SMB<br>(Pb-Free) | 2500 / Tape & Reel |
| NRVBSS26T3G | SMB<br>(Pb-Free) | 2500 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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## THERMAL CHARACTERISTICS

| Characteristic                                    | Symbol          | Value | Unit                        |
|---|-----------------|-------|-----------------------------|
| Thermal Resistance – Junction-to-Lead (Note 1)    | $R_{\theta JL}$ | 24    | $^{\circ}\text{C}/\text{W}$ |
| Thermal Resistance – Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 80    | $^{\circ}\text{C}/\text{W}$ |

- Mounted with minimum recommended pad size, PC Board FR4.
- 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

## ELECTRICAL CHARACTERISTICS

| Characteristic   | Symbol | Value                      |                             | Unit |
|--|--------|----------------------------|-----------------------------|------|
|  |        | $T_J = 25^{\circ}\text{C}$ | $T_J = 125^{\circ}\text{C}$ |      |
| Maximum Instantaneous Forward Voltage (Note 3)<br>( $i_F = 1.0\text{ A}$ )<br>( $i_F = 2.0\text{ A}$ ) | $V_F$  | 0.51<br>0.63               | 0.475<br>0.55               | V    |
| Maximum Instantaneous Reverse Current (Note 3)<br>( $V_R = 60\text{ V}$ )                              | $I_R$  | 0.2                        | 20                          | mA   |

- Pulse Test: Pulse Width  $\leq 250\ \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

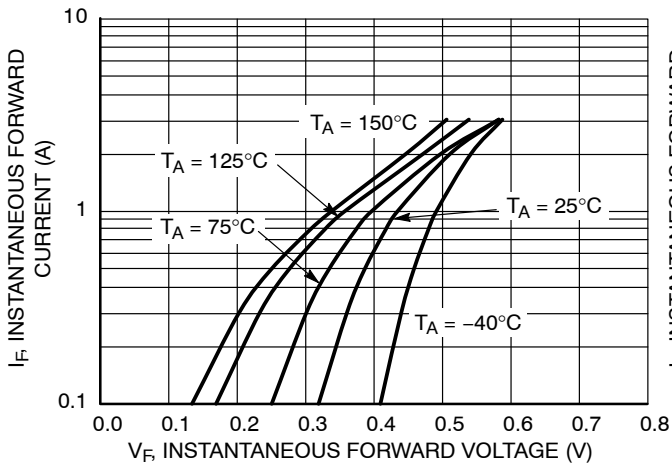


Figure 1. Typical Forward Voltage

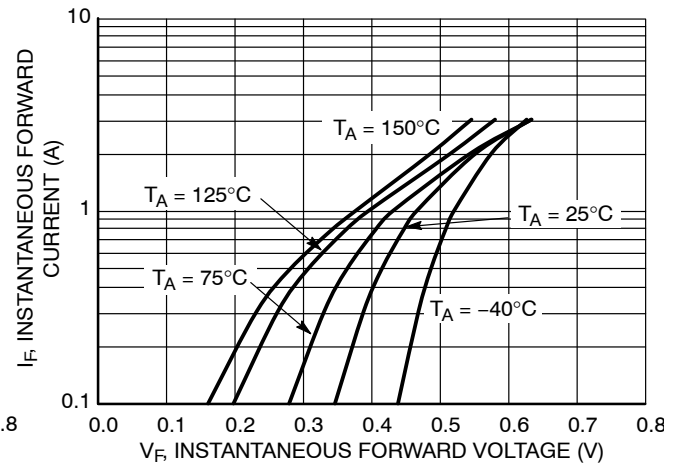


Figure 2. Maximum Forward Voltage

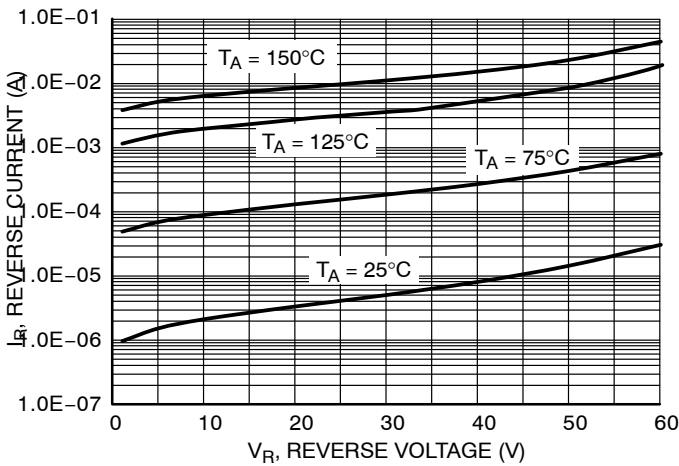


Figure 3. Typical Reverse Current

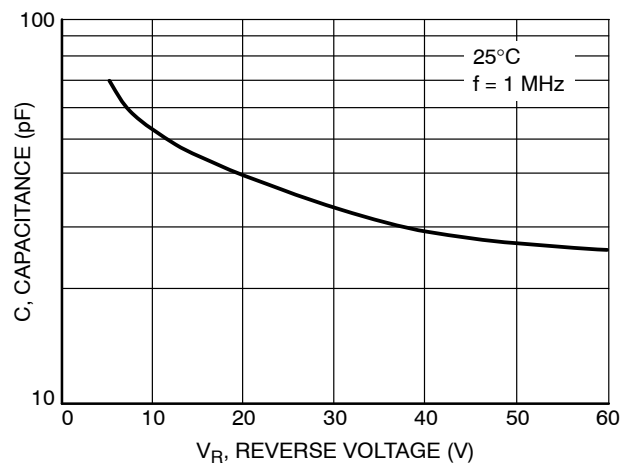


Figure 4. Typical Capacitance

# SS26T3G, NRVBSS26T3G

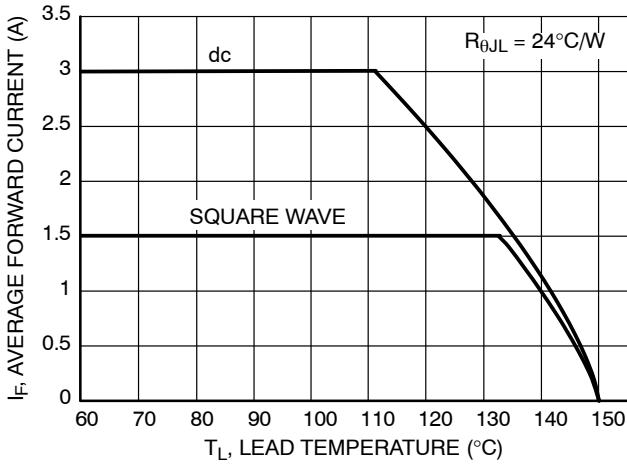


Figure 5. Current Derating – Junction to Lead

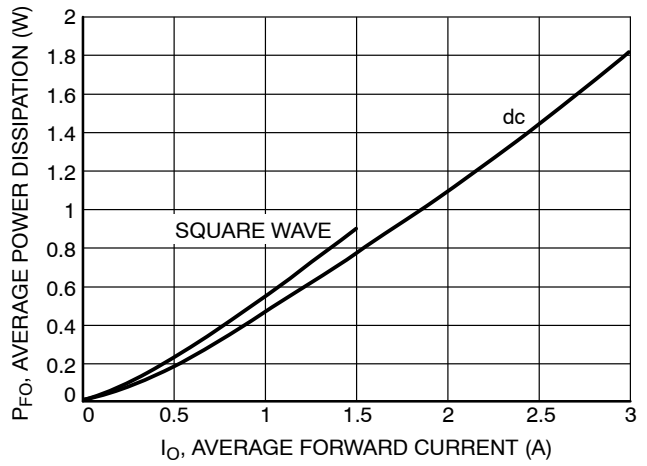


Figure 6. Forward Power Dissipation

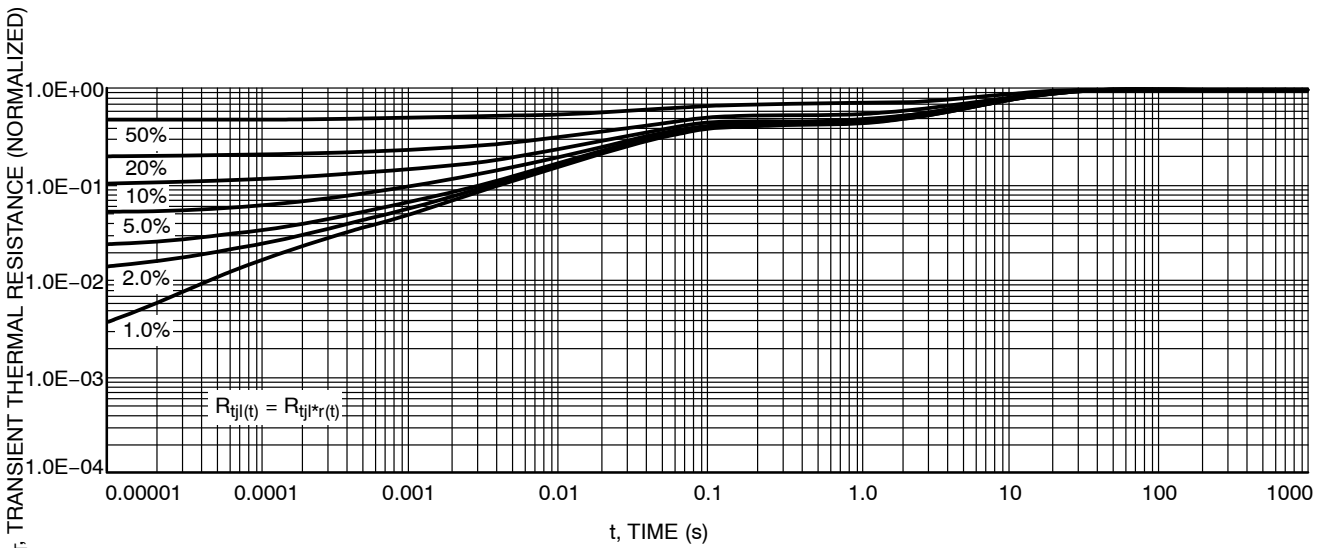


Figure 7. Thermal Response – Junction to Case

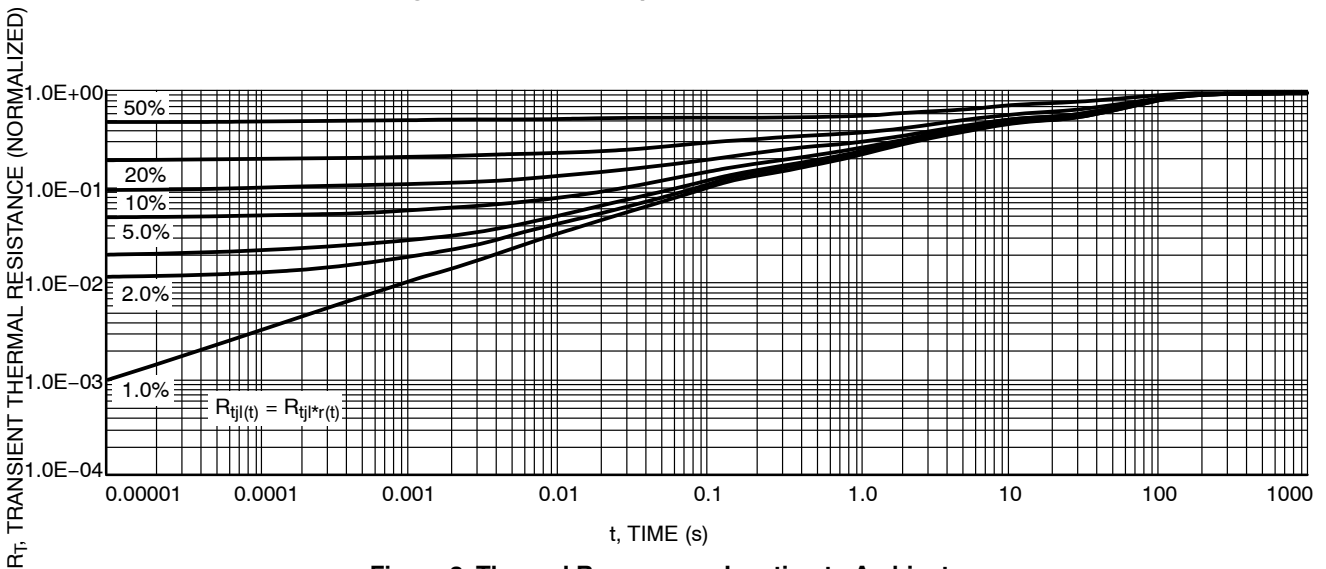
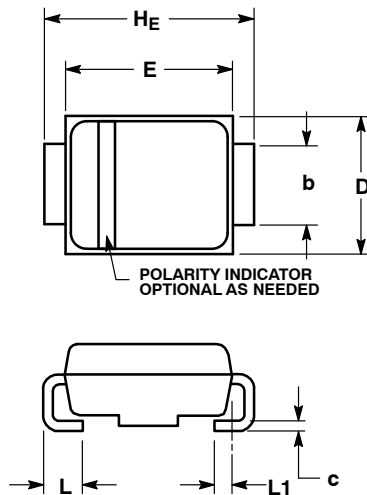


Figure 8. Thermal Response – Junction to Ambient

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## PACKAGE DIMENSIONS

**SMB**  
CASE 403A-03  
ISSUE J

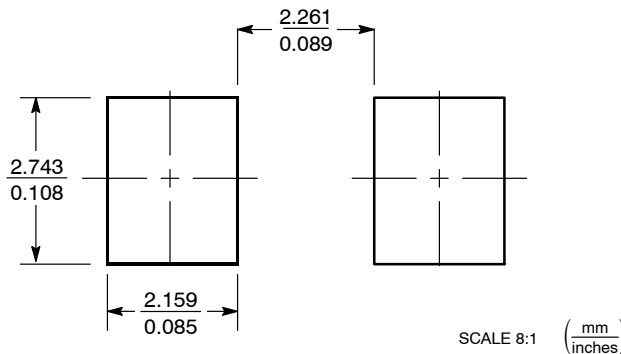


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

| DIM | MILLIMETERS |      |      | INCHES    |       |       |
|-----|-------------|------|------|-----------|-------|-------|
|     | MIN         | NOM  | MAX  | MIN       | NOM   | MAX   |
| A   | 1.95        | 2.30 | 2.47 | 0.077     | 0.091 | 0.097 |
| A1  | 0.05        | 0.10 | 0.20 | 0.002     | 0.004 | 0.008 |
| b   | 1.96        | 2.03 | 2.20 | 0.077     | 0.080 | 0.087 |
| c   | 0.15        | 0.23 | 0.31 | 0.006     | 0.009 | 0.012 |
| D   | 3.30        | 3.56 | 3.95 | 0.130     | 0.140 | 0.156 |
| E   | 4.06        | 4.32 | 4.60 | 0.160     | 0.170 | 0.181 |
| HE  | 5.21        | 5.44 | 5.60 | 0.205     | 0.214 | 0.220 |
| L   | 0.76        | 1.02 | 1.60 | 0.030     | 0.040 | 0.063 |
| L1  | 0.51 REF    |      |      | 0.020 REF |       |       |

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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